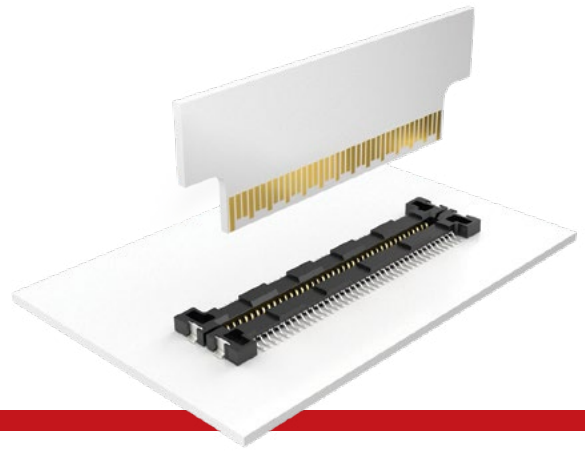


HIGH-SPEED THROUGH BOARD SOCKET

(1.00 mm) .0394" PITCH • SAL1 SERIES

14
Gbps



SAL1

Card Mates:

(1.60 mm) .062" or
(2.36 mm) .093" card

SPECIFICATIONS

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Au or Sn over 50 μ" (1.27 μm) Ni

Operating Temp Range:

-55 °C to +125 °C

Current Rating:

2.9 A per pin
(2 adjacent pins powered)

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max

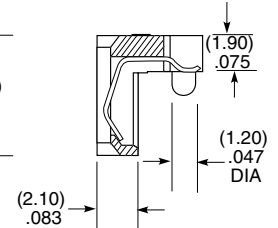
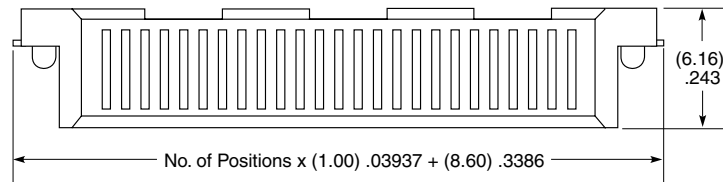
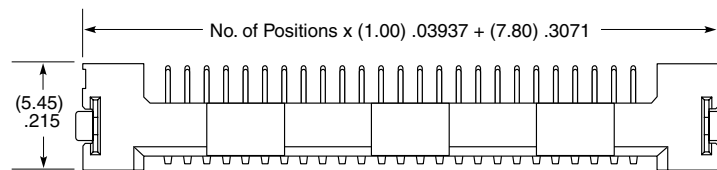


-20, -27,
-30, -40

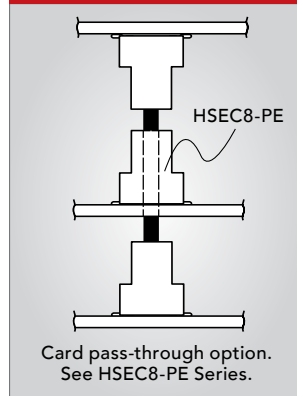
-S
= 30 μ"
(0.76 μm) Gold
on contact,
Matte tin on tail

-TR
= Tape & Reel

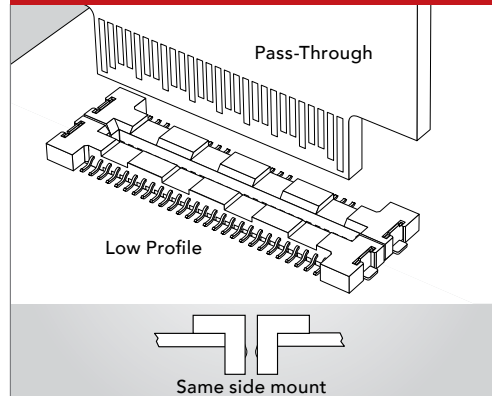
-FR
= Full Reel
Tape & Reel
(must order
maximum
quantity per
reel; contact
Samtec for
quantity breaks)



OTHER SOLUTION



APPLICATIONS



Notes:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications..

Some lengths, styles and options are non-standard, non-returnable.

View complete specifications at: samtec.com?SAL1